

霉菌对化学浸银处理印制电路板腐蚀行为影响

邹士文, 肖葵, 董超芳, 李慧艳, 李晓刚

北京科技大学腐蚀与防护中心, 北京 100083

Effect of Mold on Corrosion Behavior of Immersion Silver Finished Printed Circu

ZOU Shiwen, XIAO Kui, DONG Chaofang, LI Huiyan, LI Xiaogang

Corrosion and Protection Center, University of Science and Technology Beijing, Beijing 100083, China

[摘要](#)

[图/表](#)

[参考文献](#)

[相关文章 \(2\)](#)